

**Amendments to the Specification:**

Page 2, please add the following section between lines 11 and 13:

**BRIEF DESCRIPTION OF THE DRAWING**

Figure 1 is a side view of a heat-generating device, film and cold sink.

Page 2, please replace the paragraph starting on line 24 and continuing through line 3 of page 3 with the following replacement paragraph:

The thermal interface material of the present invention may be utilized with virtually any heat-generating component for which it is desired to dissipate the heat. In particular, the thermal interface material is useful for aiding in the dissipation of heat from heat-generating components in semiconductor devices. In such devices, as shown in Figure 1, the thermal interface material 1 forms a layer between the heat-generating component 2 and the cold sink 3 and transfers the heat to be dissipated to the cold sink.